

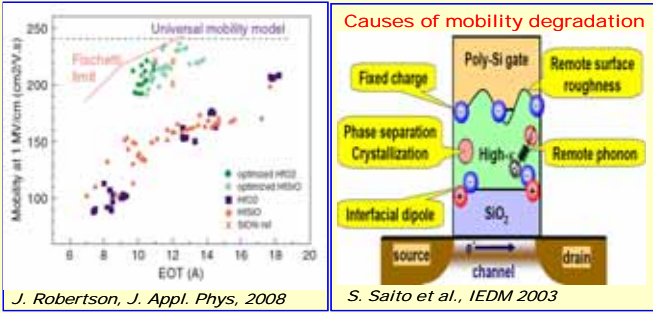


# Remote Coulomb and roughness scatterings in gate oxide scaling

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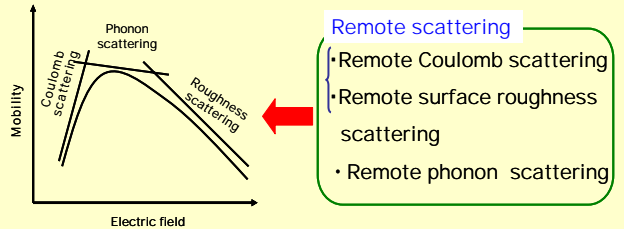
## Background

Mobility degradation is one of the main concerns in the high-k gate stacked MOSFETs.



## Purpose

Importance of Remote scattering for direct contact MOSFETs



Aim

Remote surface roughness (RSR) scattering effect on electron mobility in La<sub>2</sub>O<sub>3</sub> gate stacked MOSFETs

## Model

**RCS scattering model:** Definition: Scattering from fixed charges at the gate/high-k interface, and at the high-k/silicate interface.

**RSR scattering model:** Definition: Scattering from Roughness at the gate /high-k interface, and at the high-k/silicate interface.

**Calculation method:** Scattering potential → Relaxation time → Carrier mobility

**Parameters:** Roughness Δ, roughness correlation length L, roughness distribution R

$$R(r) = \Delta^2 e^{-\sqrt{2\pi}/L}$$

The RCS, and RSR limited mobility can be solved by Schrödinger equation and Self-consistent Poisson equation.

## Experiment

Fabrication Process and structure of Sample

**Fabrication process:**

- p-type Si substrate
- SPM, HF last treatment
- Deposition of high-k (La<sub>2</sub>O<sub>3</sub>, CeO<sub>2</sub>/La<sub>2</sub>O<sub>3</sub>)
- Metal gate deposition (W by RF sputtering)
- Gate patterning
- PMA (500°C, 30min)
- F.G. (N<sub>2</sub>:H<sub>2</sub>=97%:3%)
- S/D holing and Al wiring
- Back side Al contact

**Sample structure:**

- W / La<sub>2</sub>O<sub>3</sub> / Si
- W / CeO<sub>2</sub> / La<sub>2</sub>O<sub>3</sub> / Si

Measurement

## Results

**RCS limited electron mobility simulation and experimental result**

**Scattering potential**

**Effect of Ce capping**

	V <sub>th</sub> (V)	SS (mV/dec)	peak m <sub>eff</sub> (cm <sup>2</sup> /V.s)
With Ce capping	-0.12	70.8	205
Without CeO <sub>x</sub>	-0.41	81.6	169

Mobility in CeO<sub>2</sub>/La<sub>2</sub>O<sub>3</sub> gate stack MOSFET is larger than in single La<sub>2</sub>O<sub>3</sub> layer MOSFETs.

**Experimental result for RCS limited mobility**

**Experimental and analytic result**

**RSR limited electron mobility simulation result**

**T=35K, L=4nm, T<sub>ox</sub>=3nm**

**T=35K, L=0.5nm, T<sub>ox</sub>=3nm**

**T=35K, L=3nm, T<sub>ox</sub>=0.5nm**

**T=300K, L=4nm, T<sub>ox</sub>=0.2nm**

## Conclusion

Capping of the CeO<sub>2</sub> on La<sub>2</sub>O<sub>3</sub> layer can control the amount of the fixed charges in the gate. Therefore the RCS limited mobility can be improved by proper capping of CeO<sub>2</sub> on La<sub>2</sub>O<sub>3</sub> layer MOSFETs.

For a larger value of the roughness correlation length and for a larger value of the oxide thickness, the remote Coulomb scattering play dominant role than RSR scattering.